

# Embedded USB Mass Storage Drive (e230)

**MTEDCAR002SAJ-1M2/1M2IT, MTEDCAR004SAJ-1N2/1N2IT  
MTEDCAR008SAJ-1N2/1N2IT, MTEDCAR016SAJ-1N2/1N2IT  
MTEDCBR002SAJ-1M2/1M2IT, MTEDCBR004SAJ-1N2/1N2IT  
MTEDCBR008SAJ-1N2/1N2IT, MTEDCBR016SAJ-1N2/1N2IT  
MTEDCBE002SAJ-1M2/1M2IT, MTEDCBE004SAJ-1N2/1N2IT  
MTEDCBE008SAJ-1N2/1N2IT, MTEDCBE016SAJ-1N2/1N2IT  
MTEDCAE002SAJ-1M2/1M2IT, MTEDCAE004SAJ-1N2/1N2IT  
MTEDCAE008SAJ-1N2/1N2IT, MTEDCAE016SAJ-1N2/1N2IT**

## Features

- Micron® NAND Flash
- Interface: Universal Serial Bus (USB) Specification, Revision 2.0
- USB support
  - USB Specification, Revisions 2.0, 1.1
  - USB Mass Storage Class Specification, Revision 1.0
- Performance
  - Sequential READ<sup>1</sup>: 30 MB/s
  - Sequential WRITE<sup>1</sup>: 22 MB/s (2GB and 4GB); 28 MB/s (8GB and 16GB)
- Reliability: >1 million device hours mean time between failure (MTBF)
- Endurance: useful operating life of at least 5 years under the following conditions:
  - 8760 power-on hours per year
  - Active 100% of power-on hours
  - Typical operating conditions<sup>2</sup>: 2GB module: 16 GB/day; 4GB module: 32 GB/day; 8GB module: 64 GB/day; 16GB module: 128 GB/day
- Static and dynamic wear-leveling
- 15-bit error correction code (ECC)
- Reliability reporting

- Capacity (unformatted)<sup>3</sup>: 2GB, 4GB, 8GB, or 16GB
- Form factor
  - Standard (36.9mm x 26.6mm x 9.6mm)
  - Low profile (36.9mm x 26.6mm x 5.8mm)
- Voltage: 5V ±5% and 3.3V ±5%
- Operating temperature
  - Commercial (0°C to +70°C)
  - Industrial (–40°C to +85°C)

- Notes:
1. Typical transfer rate measured with H2BENCH 3.6.
  2. Assumes that 70% of total usable drive capacity contains static files.
  3. 1GB = 1 billion bytes; formatted capacity is less.

**Warranty:** Contact your Micron sales representative for further information regarding the product, including product warranties.



## Part Numbering Information

Micron's embedded USB drives are available in different configurations and densities. Visit [www.micron.com](http://www.micron.com) for a list of valid part numbers.

**Table 1: Part Number Example**

| Part Number Category |                |                 |                   |               |                 |                |             |                |          |                             |                   |
|----------------------|----------------|-----------------|-------------------|---------------|-----------------|----------------|-------------|----------------|----------|-----------------------------|-------------------|
| Micron Technology    | Product Family | Drive Interface | Drive Form Factor | Drive Density | NAND Flash Type | Product Family | Sector Size | NAND Component | Revision | Operating Temperature Range | Production Status |
| MT                   | ED             | C               | AE                | 002           | S               | AJ             | -1          | M              | 1        | IT                          | ES                |

**Table 2: Part Number Information Scheme**

| Part Number Category        | Category Details                                                                                                                                                                                                                                                   |
|-----------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Micron Technology           | Micron Technology                                                                                                                                                                                                                                                  |
| Product Family              | ED = Embedded drive                                                                                                                                                                                                                                                |
| Drive Interface             | C = USB 2.0                                                                                                                                                                                                                                                        |
| Drive Form Factor           | AE = Embedded USB: 5V standard profile (36.9mm x 26.6mm x 9.6mm)<br>BE = Embedded USB: 5V low profile (36.9mm x 26.6mm x 5.8mm)<br>AR = Embedded USB: 3V standard profile (36.9mm x 26.6mm x 9.6mm)<br>BR = Embedded USB: 3V low profile (36.9mm x 26.6mm x 5.8mm) |
| Drive Density               | 002 = 2GB<br>004 = 4GB<br>008 = 8GB<br>016 = 16GB                                                                                                                                                                                                                  |
| NAND Flash Type             | S = SLC                                                                                                                                                                                                                                                            |
| Product Family              | AJ = Option J                                                                                                                                                                                                                                                      |
| Sector Size                 | 1 = 512-byte                                                                                                                                                                                                                                                       |
| NAND Component              | M = 8Gb; x8; 3.3V<br>N = 16Gb; x8; 3.3V                                                                                                                                                                                                                            |
| Revision                    | 1 = First generation<br>2 = Second generation<br>3 = Third generation                                                                                                                                                                                              |
| Operating Temperature Range | Blank = Commercial (0°C to 70°C)<br>IT = Industrial (40°C to 85°C)                                                                                                                                                                                                 |
| Production Status           | Blank = Production<br>ES = Engineering sample<br>MS = Mechanical sample                                                                                                                                                                                            |

## General Description

Micron embedded universal serial bus (USB) mass storage drives provide 2GB, 4GB, 8GB, or 16GB of USB 2.0-compatible memory storage in a small form factor. The embedded USB drive is an ideal solution for applications that require low cost and high reliability. Typical applications include PC caching and boot drives for embedded computing, server, and networking systems.

High performance, reliability, and easy implementation make Micron embedded USBs an ideal storage solution. To consistently deliver the best possible performance, the embedded USB uses only SLC NAND Flash, and all densities use two x8 NAND channels to the controller. In addition to being fast, SLC NAND Flash offers solid reliability, coupled with ECC and wear leveling. The USB system interface is widely available in many system designs and is easy to implement, enabling rapid time to market.

The embedded USB consists of two TSOP-packaged Micron NAND Flash components, a USB controller, and a 10-pin USB connector on a PCB. Different densities are available depending on the number of die in each package and the density of each NAND Flash die. The drive operates at 5V  $\pm$ 5% or 3.3V  $\pm$ 5%. It uses industry-standard 10-pin connectors and supports USB Specification, Revision 2.0. It is also backward compatible with Revision 1.1 and can be used with operating systems that support USB Mass Storage Class Specification, Revision 1.0.

**Figure 1: Functional Block Diagram**



**Table 3: Nominal Package Dimensions, Density, and Weight**

|             | Value                               | Unit |
|-------------|-------------------------------------|------|
| Height      | 9.6 (standard)<br>5.8 (low profile) | mm   |
| Width       | 26.6                                | mm   |
| Length      | 36.9                                | mm   |
| Density     | 2, 4, 8, 16                         | GB   |
| Unit weight | 4.5                                 | g    |

**Figure 2: Pin Assignments: 2 x 5 Connector**



Note: 1. Diagram not to scale.

**Table 4: Signal/Pin Descriptions**

| Symbol                     | Type   | Function                                                                                                                                                                                |
|----------------------------|--------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| USB data (+), USB data (-) | I/O    | <b>Data inputs/outputs:</b> The bidirectional I/Os transfer address, data, and instruction information. Data is output only during READ operations; at other times the I/Os are inputs. |
| V <sub>CC</sub>            | Supply | V <sub>CC</sub> power supply pin.                                                                                                                                                       |
| V <sub>SS</sub>            | Supply | V <sub>SS</sub> ground connection                                                                                                                                                       |
| NC                         | –      | <b>No connect:</b> NC pins are not internally connected. These pins can be driven or left floating.                                                                                     |
| Key                        | –      | This pin is keyed.                                                                                                                                                                      |

## Error Management

The embedded USB incorporates advanced technology for defect and error management. It uses various combinations of hardware-based error correction algorithms and firmware-based wear-leveling algorithms.

Over the life of the drive, uncorrectable errors may occur. An uncorrectable error is defined as data that is reported as successfully programmed to the drive, but when it is read out of the drive, the data differs from what was programmed. See the Uncorrectable Bit Error Rate Table.

The mean time between failures (MTBF) can be predicted based on component reliability data obtained by following the methods referenced in the Telecordia SR-332 reliability prediction procedures for electronic equipment.

**Table 5: System Reliability**

| Density | MTFB (Operating Hours)  |
|---------|-------------------------|
| 2–16GB  | >1 million device hours |

**Table 6: Uncorrectable Bit Error Rate**

| Uncorrectable Bit Error Rate (BER) <sup>1</sup> | Operation |
|-------------------------------------------------|-----------|
| <1 bit error in 10 <sup>15</sup> bits           | READ      |

Note: 1. BER is measured with a WRITE-to-READ ratio of 1:1.

## Wear-Leveling Algorithm

The controller adds a built-in RAM register unit to record the erase count of each block. Accordingly, the controller can decide the frequency of wear leveling and choose the proper blocks to swap. This technique successfully averages the erase count of the data blocks. Also, an enhanced wear leveling algorithm now includes most static blocks in the recycling pool. Increasing the number of blocks makes the wear-leveling algorithm more robust, and in turn extends product life.

## Electrical Characteristics

Stresses greater than those listed may cause permanent damage to the drive. This is a stress rating only, and functional operation of the drive at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**Table 7: Absolute Maximum Ratings**

| Parameter/Condition            | Symbol          | Min  | Max  | Unit |
|--------------------------------|-----------------|------|------|------|
| V <sub>CC</sub> supply voltage | V <sub>CC</sub> | -0.6 | 5.25 | V    |

**Table 8: DC and Operating Characteristics**

| Parameter/Condition | Symbol           | Min | Typ | Max | Unit | Condition                 |
|---------------------|------------------|-----|-----|-----|------|---------------------------|
| Standby current     | I <sub>sb</sub>  | -   | 60  | 70  | mA   | V <sub>CC</sub> = 3V      |
|                     |                  | -   | 50  | 60  | mA   | V <sub>CC</sub> = 5V      |
| Active current      | I <sub>CC1</sub> | -   | 100 | 120 | mA   | V <sub>CC</sub> = 3V / 5V |

**Table 9: Recommended Operating Conditions**

| Parameter/Condition            | Symbol          | Min             | Typ  | Max  | Unit |    |
|--------------------------------|-----------------|-----------------|------|------|------|----|
| Operating temperature          | Commercial      | T <sub>A</sub>  | 0    | -    | 70   | °C |
|                                | Industrial      |                 | -40  | -    | 85   | °C |
| V <sub>CC</sub> supply voltage | 5V              | V <sub>CC</sub> | 4.75 | 5.00 | 5.25 | V  |
|                                | 3.3V            | V <sub>CC</sub> | 2.85 | 3.3  | 3.5  | V  |
| Ground supply voltage          | V <sub>SS</sub> | 0               | 0    | 0    | V    |    |

**Table 10: Shock and Vibration**

| Parameter/Condition | Specification   |
|---------------------|-----------------|
| Shock               | 1500g/0.5ms     |
| Vibration           | 5-500Hz at 3.1G |

### Compliance

Micron embedded USB drives comply with the following requirements:

- CE (Europe): EN55022, 2006 Class B and EN55024, 1998 + A1: 2001 + A2:2003
- FCC: CFR Title 47, Part 15, ICES-003, all Class B
- UL (US): approval to UL-60950-1, 2nd Edition, 2007-03-27, IEC 60950-1:2005, 2nd Edition
- RoHS, “green” package

### Configuration

The following configuration options are available:

- Micron's embedded USB drive can be configured as a boot drive.
- The standard fix configuration should be mounted as local drive.

**Note:** The embedded USB drive cannot be configured as a removable drive.

## Mechanical Information

The standard 10-pin (2 x 5) female electrical connector has a height of 7.4mm and a pitch of 2.54mm. It supports the standard USB 2.0 interface. The low profile 10-pin (2 x 5) female electrical connector has a height of 3.6mm and a pitch of 2.0mm. It supports the standard USB 2.0 interface. A mounting hole is also provided on the PCB for a stable, reliable connection to the mounting board.

The motherboard pin headers listed in Table 9 are compatible with Micron's embedded USB drives. Pin headers that are not listed may also be compatible.

**Table 11: Compatible Pin Headers**

| Manufacturer | Profile     | Part Number       | Type      |
|--------------|-------------|-------------------|-----------|
| Pinrex       | Standard    | 212-92-05GB01     | SMT       |
|              |             | 210-92-05GB01     | Straight  |
| Amtek        | Standard    | PHIFS25-205GB     | Press fit |
|              |             | PHIS25-205GB      | Straight  |
| Samtec       | Low profile | TMM-105-01-S-D-02 | Straight  |

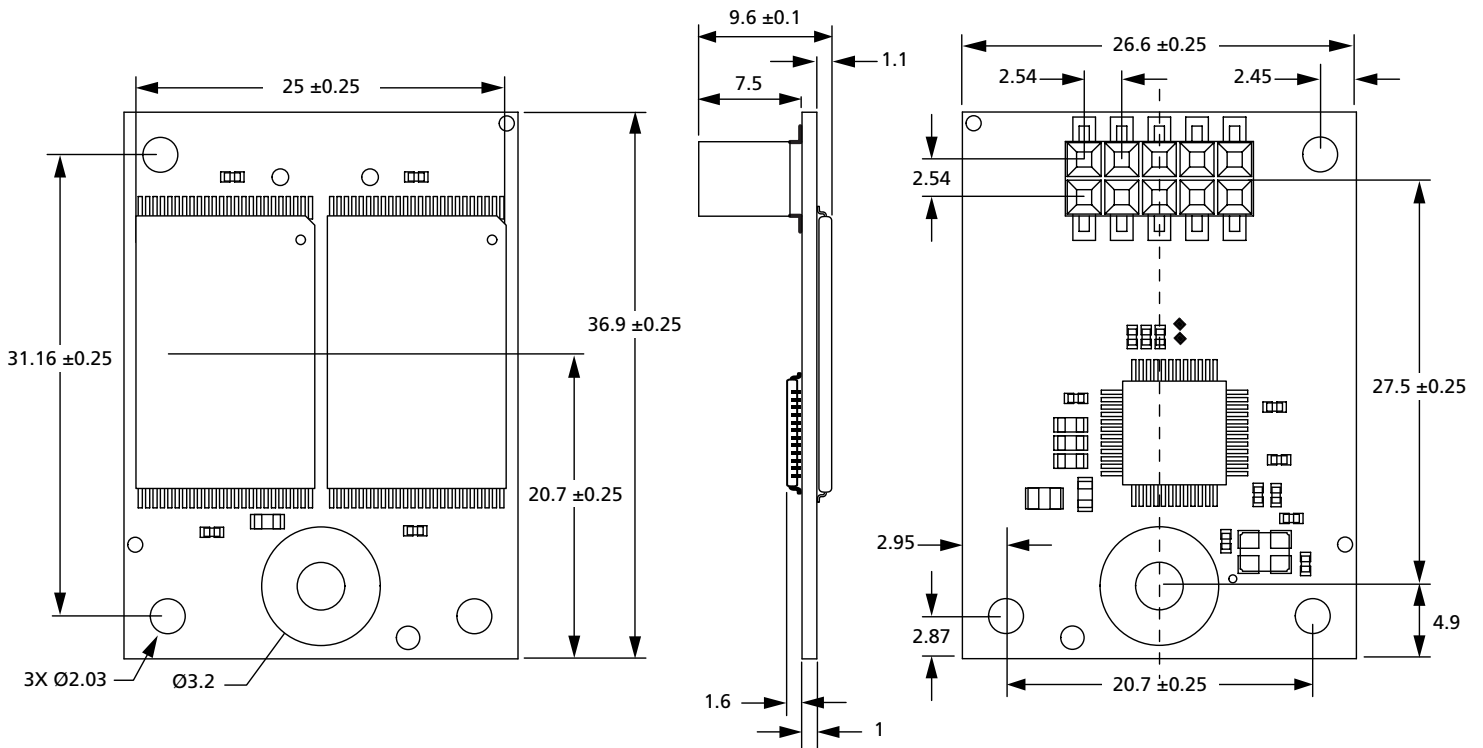
## Reference Documents

Reference documentation for the USB 2.0 standard (USB 2.0 specification, technical documents, compliance test procedures, and other related documents) can be found at [www.usb.org/developers/docs](http://www.usb.org/developers/docs).



## Package Dimensions

**Figure 3: Embedded USB Package, Standard Profile**



Note: 1. All dimensions are in millimeters.

**Figure 4: Embedded USB Package, Low Profile**



Note: 1. All dimensions are in millimeters.



## **Revision History**

### **Rev. D – 4/13**

- Updated the package drawing
- Updated densities in order information

### **Rev. C, Advance – 7/12**

- Added 3V information to DC and Operating Conditions table

### **Rev. B, Advance – 9/11**

- Added low profile and 3V information

### **Rev. A, Advance – 4/11**

- Initial release

8000 S. Federal Way, P.O. Box 6, Boise, ID 83707-0006, Tel: 208-368-3900  
[www.micron.com/productsupport](http://www.micron.com/productsupport) Customer Comment Line: 800-932-4992  
Micron and the Micron logo are trademarks of Micron Technology, Inc.  
All other trademarks are the property of their respective owners.

This data sheet contains minimum and maximum limits specified over the power supply and temperature range set forth herein. Although considered final, these specifications are subject to change, as further product development and data characterization sometimes occur.

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)  
Email: [org@lifeelectronics.ru](mailto:org@lifeelectronics.ru)